

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application. In this listing, no claims have been deleted and new claims 20-24 have been added. Claims 1-24 now are pending in this application.

1. (Currently Amended) A backlight assembly for illuminating a liquid crystal panel, comprising:

a frame having a frame body in which are embedded a plurality of contact pads, a portion of each of the pads being integrally surrounded by a material comprising the frame body, wherein the frame body is configured to assemble the liquid crystal panel with the backlight assembly;

a light-guide plate mounted to the frame; and

one or more light-emitting device connected to the contact pads and respectively having a light-irradiating surface facing a first surface of the light-guide plate, light irradiated from the one or more light-emitting devices emerging out through a second surface of the light-guide plate towards the liquid crystal panel.

2. (Original) The backlight assembly according to claim 1, comprising a reflective sheet placed at a side of the light-guide plate to direct light towards the liquid crystal panel.

3. (Original) The backlight assembly according to claim 1, wherein the one or more light-emitting device is placed at a side of the light-guide plate opposite to the side of the liquid crystal panel.

4. (Original) The backlight assembly according to claim 3, wherein the one or more light-emitting device is positioned proximate to a side edge of the light-guide plate.

5. (Original) The backlight assembly according to claim 4, wherein a reflection member is provided in an area of the side edge of the light-guide plate to reflect light irradiated from the one or more light-emitting device.

6. (Original) The backlight assembly according to claim 5, wherein the reflection member is a reflective coating.

7. (Original) The backlight assembly according to claim 5, wherein the reflection member is a surface of the light-guide plate inclined at an angle.

8. (Original) The backlight assembly according to claim 3, wherein the light-guide plate includes one or more recessed cavity on the first surface for accommodating the light-irradiating surface of the one or more light-emitting device.

9. (Original) The backlight assembly according to claim 1, wherein the first surface of the light-guide plate is a side edge surface of the light-guide plate.

10. (Original) The backlight assembly according to claim 1, wherein the frame body is formed by injection-molding.

11. (Original) The backlight assembly according to claim 1, wherein the contact pads include resilient bent portions to which the one or more light-emitting device is connected by contact engagement.

12. (Original) The backlight assembly according to claim 1, wherein the one or more light-emitting device is connected to the contact pads by soldering.

13. (Original) The backlight assembly according to claim 1, wherein the contact pads are made of a conductive metal or metallic alloy.

14. (Original) The backlight assembly according to claim 1, wherein the one or more light-emitting device includes a light-emitting diode.

15. (Currently Amended) A frame structure for a backlight assembly, comprising:
a frame body configured to assemble a liquid crystal panel with the backlight assembly;
and

a plurality of contact pads embedded in the frame body, a portion of each of the pads
being integrally surrounded by a material comprising the frame body, wherein the contact pads
externally connect to a power source and are configured to receive the mount of one or more
light-emitting device.

16. (Original) The frame structure according to claim 15, wherein the frame body is
formed by injection-molding.

17. (Original) The frame structure according to claim 15, wherein the contact pads
include resilient bent portions to which the one or more light-emitting device is connected by
engagement.

18. (Original) The frame structure according to claim 15, wherein the contact pads are
made of a conductive metal or metallic alloy.

19. (Original) The frame structure according to claim 15, wherein the one or more light-emitting device includes a light-emitting diode.

20. (New) A frame structure for a backlight assembly, comprising:

a frame body configured to assemble a liquid crystal panel with the backlight assembly;
and

a plurality of contact pads configured to externally connect to a power source and receive the mount of one or more light-emitting device, wherein the frame body is molded over a portion of one or more of the contact pads.

21. (New) The frame structure according to claim 20, wherein the frame body is formed by injection-molding.

22. (New) The frame structure according to claim 20, wherein the contact pads include resilient bent portions configured to connect to one or more light-emitting device by engagement.

23. (New) The frame structure according to claim 20, wherein the contact pads are made of a conductive metal or metallic alloy.

24. (New) The frame structure according to claim 20, wherein the one or more light-emitting device includes a light-emitting diode.